



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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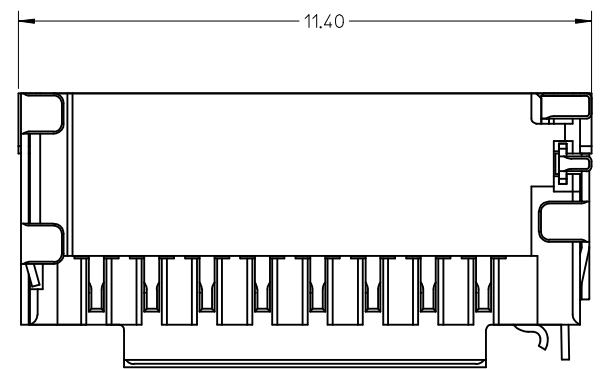
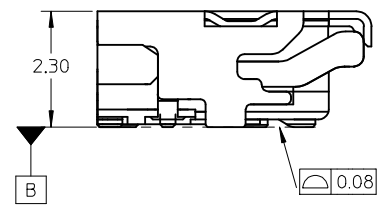
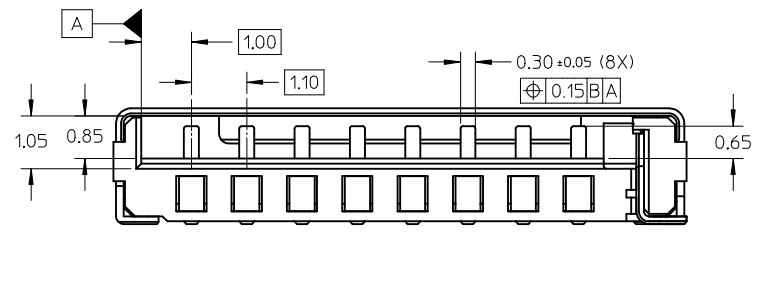
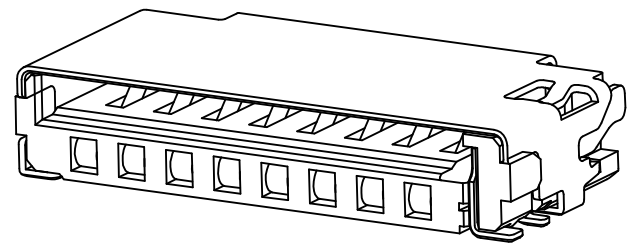
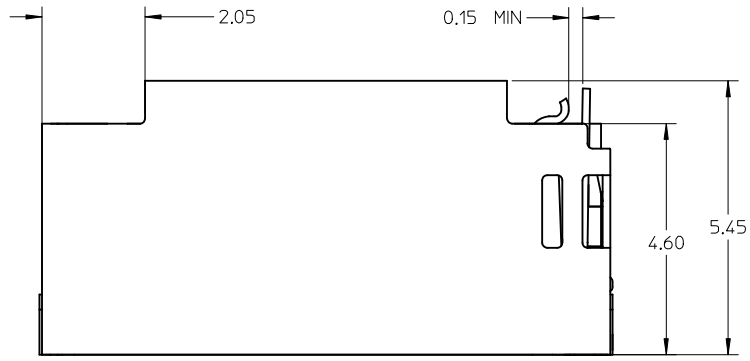
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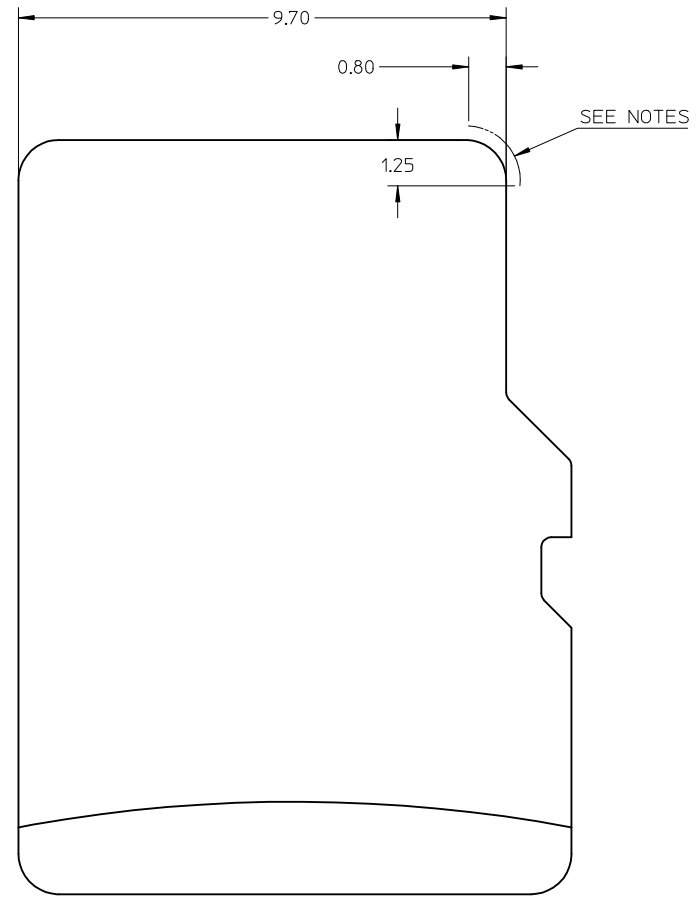
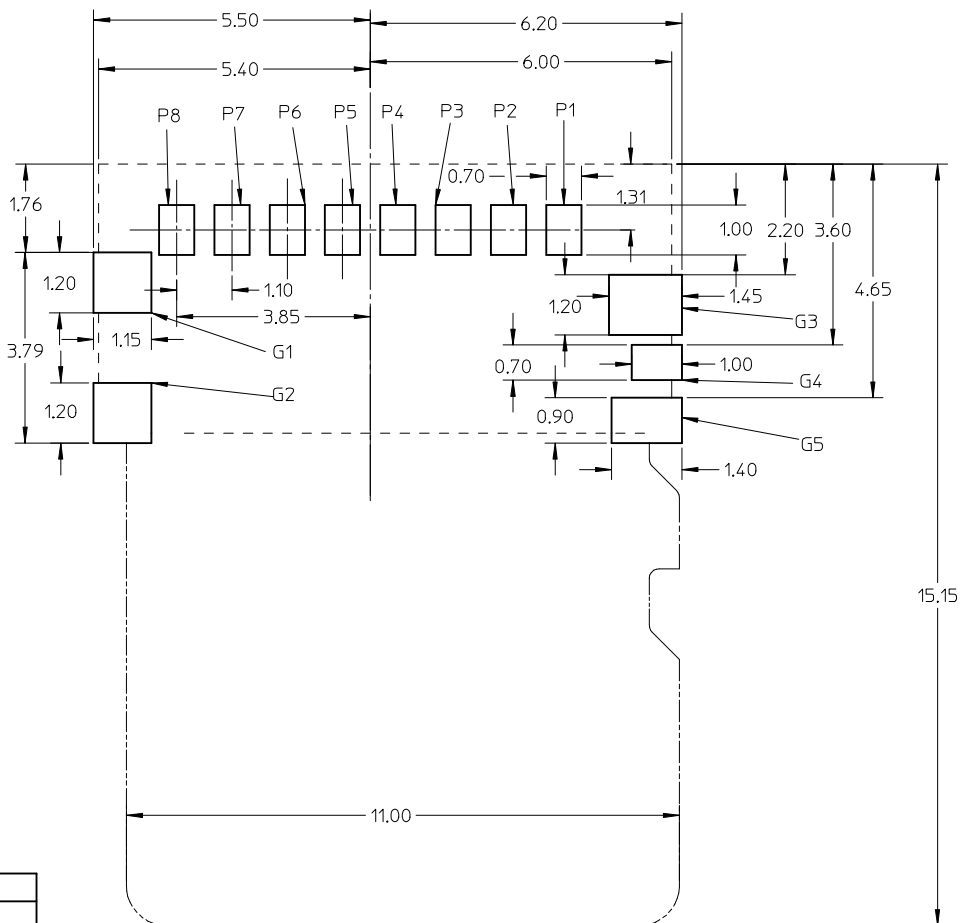
NOTES:

1. MATERIAL:
 - 1-1 HOUSING: LCP, 30% G/F, UL 94V-0, BLACK
 - 1-2 SIGNAL TERMINAL AND DETECT TERMINAL: PHOSPHOR BRONZE
 - 1-3 METAL SHELL: STAINLESS STEEL
2. FINISH:
 - 2-1 SIGNAL TERMINAL: 1.25 MICRON NICKEL MIN UNDER-PLATED, CONTACT AREA SEE TABLE, GOLD FLASH ON SOLDER AREA.
 - 2-2 METAL SHELL: GOLD FLASH OVER NICKEL ON SOLDER AREA.
 - 2-3 DETECT PIN: 1.25 MICRON NICKEL MIN UNDER-PLATED GOLD FLASH PLATED ON CONTACT AREA, TIN PLATED ON SOLDER AREA.
3. PRODUCT SPECIFICATION: PS-47309-001.
4. PACKAGE SPECIFICATION: PK-47571-001.
5. PRODUCT COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

47571-0101	0.38 MICRON MIN. GOLD PLATING
47571-0001	0.76 MICRON MIN. GOLD PLATING
47571-2001	0.1 MICRON MIN. GOLD PLATING
P/N	CONTACT AREA PLATING

ADD PART NUMBER EC NO: SH2012-0261 DRWG: GLLI CHKD: APPR: AYIN REV	2012/02/10 2012/02/23	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_D=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY	DATE	TITLE			
	4 PLACES		± ---	± ---	GLL I	2012/02/10	TFR HEADER WITH DETECT PIN			
	3 PLACES		± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.15	± ---	XQ ZHANG	2012/02/10	MOLEX INCORPORATED					
1 PLACE	± 0.25	± ---	APPROVED BY	DATE						
		ANGULAR ± 3 °		AYIN	2012/02/23	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-47571-001	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1



G5	DET
G4	POL
G3	GND
G2	GND
G1	GND
P8	DAT1
P7	DAT0
P6	VSS
P5	CLK
P4	VDD
P3	CMD
P2	CD/DAT3
P1	DAT2
NAME	TYPE
PIN ASSIGNMENT	

----- CONNECTOR PROFILE
 - - - - - CARD PROFILE

NOTES:
 NO CONDUCTIVE EXPOSURE TRACE IS ALLOWED ON THE SIDE FACE OF THE CARD AT THIS AREA.

SEE SHEET 1
EC NO: SH2012-0261
DRW:GLL1
CHKD:
APP:AYIN
REV

QUALITY SYMBOLS
$\nabla = 0$
$\nabla = 0$
$\nabla = 0$
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.15 ± ---
1 PLACE ± 0.25 ± ---
ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS
MM ONLY	1:1	METRIC
DRAWN BY	DATE	TITLE
GLL1	2012/02/10	TFR HEADER WITH DETECT PIN
CHECKED BY	DATE	
XQ ZHANG	2012/02/10	
APPROVED BY	DATE	
AYIN	2012/02/23	
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE SHEET 1	SD-47571-001	2 OF 2

THIRD ANGLE PROJECTION
MOLEX INCORPORATED
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION